



FQB17N08 / FQI17N08

80V N-Channel MOSFET

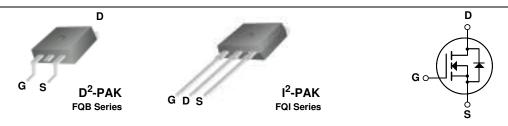
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as automotive, high efficiency switching for DC/DC converters, and DC motor control.

Features

- 16.5A, 80V, $R_{DS(on)} = 0.115\Omega$ @ $V_{GS} = 10$ V
- Low gate charge (typical 12 nC)
- Low Crss (typical 28 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB17N08 / FQI17N08	Units	
V _{DSS}	Drain-Source Voltage		80	V	
I _D	Drain Current - Continuous (T _C = 25°	°C)	16.5	Α	
	- Continuous (T _C = 10	0°C)	11.6	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	66	Α	
V _{GSS}	Gate-Source Voltage		± 25	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	100	mJ	
I _{AR}	Avalanche Current	(Note 1)	16.5	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	6.5	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.5	V/ns	
P_{D}	Power Dissipation (T _A = 25°C) *		3.13	W	
	Power Dissipation (T _C = 25°C)		65	W	
	- Derate above 25°C		0.43	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.31	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

-	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	80			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25°C		0.08		V/°C
I _{DSS}	- 0.444 5.40	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 64 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 8.25 A		0.088	0.115	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 30 V, I _D = 8.25 A (Note 4)		5.3		S
C _{oss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		120 28	155 35	pF
C _{rss}		f = 1.0 MHz		-		- '
Curital				•	33	pF
OWITCH	ing Characteristics				33	pF
t _{d(on)}	ing Characteristics Turn-On Delay Time	V - 40 V I - 16 5 A		4.8	20	pF
t _{d(on)}	1	$V_{DD} = 40 \text{ V}, I_{D} = 16.5 \text{ A},$ $R_{D} = 25 \Omega$		4.8		•
t _{d(on)}	Turn-On Delay Time	V_{DD} = 40 V, I_{D} = 16.5 A, R_{G} = 25 Ω			20	ns
$t_{d(on)}$ t_r $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time			60	20	ns ns
$t_{d(on)}$ t_r $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time	$R_G = 25~\Omega$ (Note 4, 5)		60 15	20 130 40	ns ns
$t_{d(on)}$ t_{r} $t_{d(off)}$ t_{f} Q_{g}	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	R_G = 25 Ω (Note 4, 5) V_{DS} = 64 V, I_D = 16.5 A,		60 15 25	20 130 40 60	ns ns ns
$t_{d(on)}$ t_{r} $t_{d(off)}$ t_{f}	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$R_G = 25~\Omega$ (Note 4, 5)		60 15 25 12	20 130 40 60 15	ns ns ns ns
$\begin{array}{c} t_{d(on)} \\ t_r \\ t_{d(off)} \\ \end{array}$ $\begin{array}{c} t_f \\ Q_g \\ Q_{gs} \\ Q_{gd} \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_G = 25~\Omega \label{eq:reconstruction}$ (Note 4, 5) $V_{DS} = 64~V,~I_D = 16.5~A,$ $V_{GS} = 10~V \label{eq:reconstruction}$ (Note 4, 5)		60 15 25 12 2.7	20 130 40 60 15	ns ns ns ns
$t_{d(on)}$ t_r $t_{d(off)}$ t_f Q_g Q_{gs} Q_{gd}	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 64~V,~I_D = 16.5~A,~V_{GS} = 10~V \label{eq:VDS}$ (Note 4, 5) and Maximum Ratings		60 15 25 12 2.7	20 130 40 60 15 	ns ns ns ns
$\begin{array}{c} t_{d(on)} \\ t_r \\ \end{array}$ $\begin{array}{c} t_{d(off)} \\ t_f \\ \\ Q_g \\ \\ Q_{gs} \\ \\ Q_{gd} \\ \end{array}$ $\begin{array}{c} \textbf{Drain-S} \\ I_S \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar Maximum Continuous Drain-Source Diode	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 64~V, I_D = 16.5~A, \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$	 	60 15 25 12 2.7 5.4	20 130 40 60 15 	ns ns ns nc nC
$\begin{array}{c} t_{d(on)} \\ t_r \\ \end{array}$ $\begin{array}{c} t_{d(off)} \\ t_f \\ \\ Q_g \\ \\ Q_{gs} \\ \\ Q_{gd} \\ \end{array}$ $\begin{array}{c} \textbf{Drain-S} \\ I_{SM} \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar Maximum Continuous Drain-Source Diode F	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 64~V, I_D = 16.5~A, \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$		60 15 25 12 2.7 5.4	20 130 40 60 15 	ns ns ns nc nC
$\begin{array}{c} t_{d(on)} \\ t_r \\ \\ t_{d(off)} \\ t_f \\ \\ Q_g \\ \\ Q_{gs} \\ \\ Q_{gd} \\ \\ \\ \textbf{Drain-S} \\ \\ I_S \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics ar Maximum Continuous Drain-Source Diode	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 64~V, I_D = 16.5~A, \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$	 	60 15 25 12 2.7 5.4	20 130 40 60 15 	ns ns ns nc nC nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 0.5mH, I_{AS} = 16.5A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 16.5A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

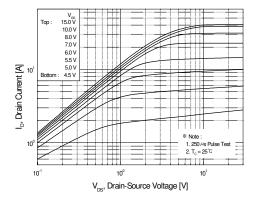


Figure 1. On-Region Characteristics

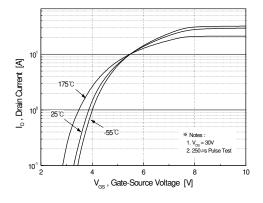


Figure 2. Transfer Characteristics

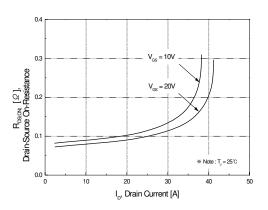


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

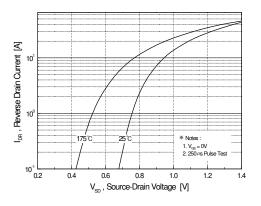


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

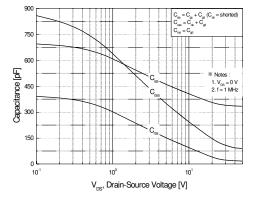


Figure 5. Capacitance Characteristics

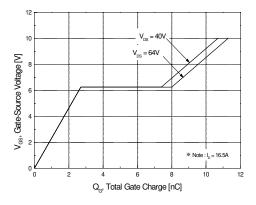
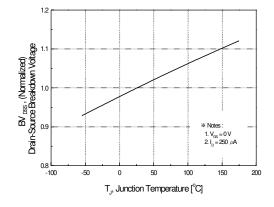


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)



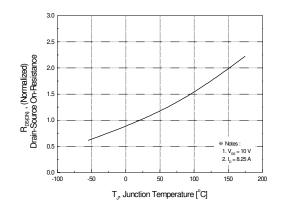
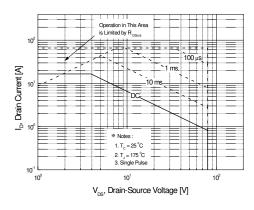


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



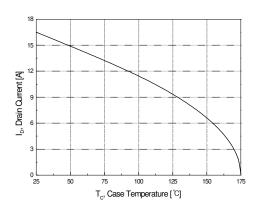


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

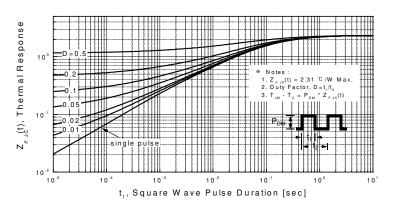
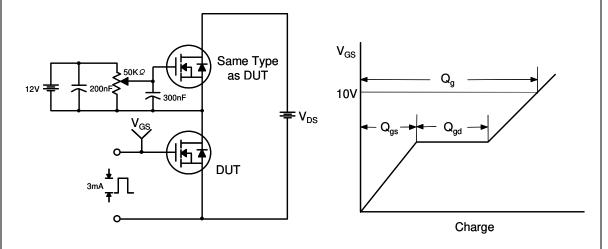


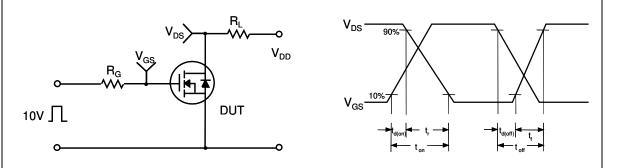
Figure 11. Transient Thermal Response Curve

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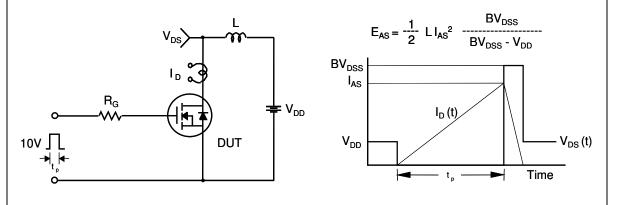
Gate Charge Test Circuit & Waveform



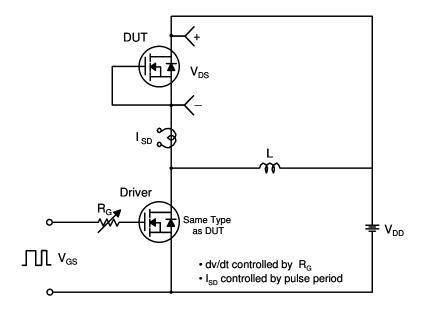
Resistive Switching Test Circuit & Waveforms

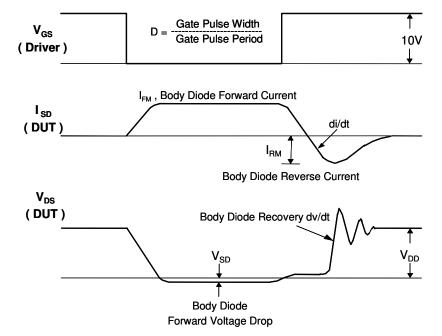


Unclamped Inductive Switching Test Circuit & Waveforms

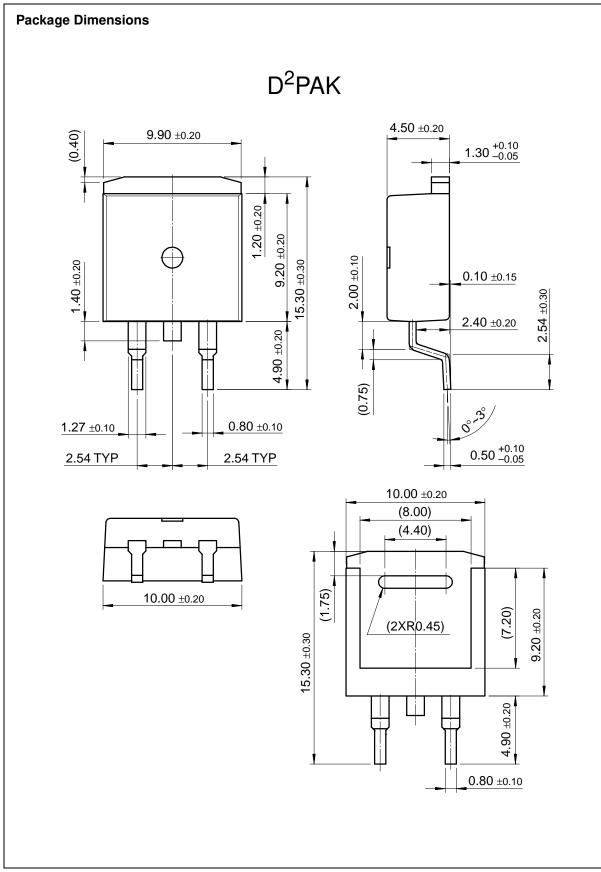


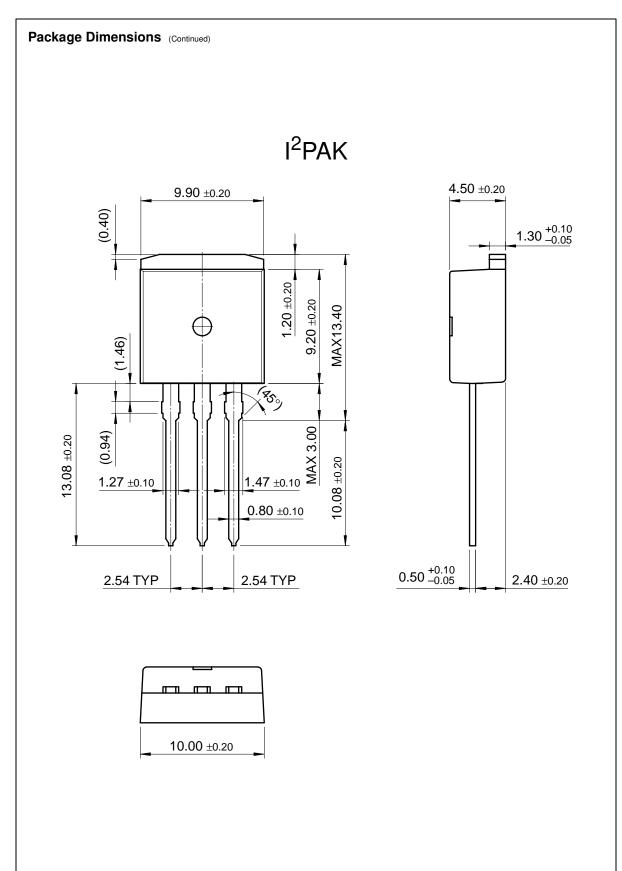
Peak Diode Recovery dv/dt Test Circuit & Waveforms





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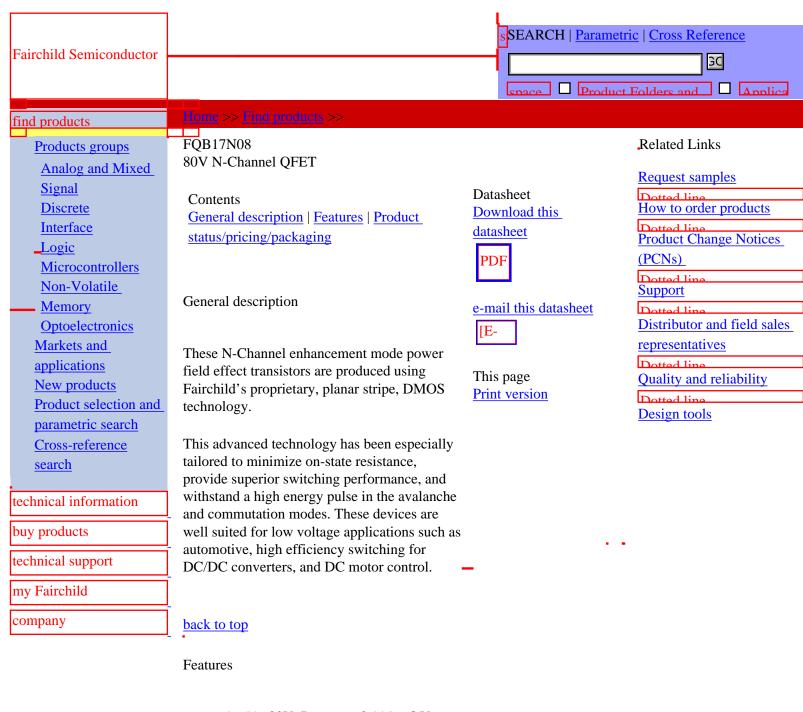
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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- Low Crss (typical 28pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating

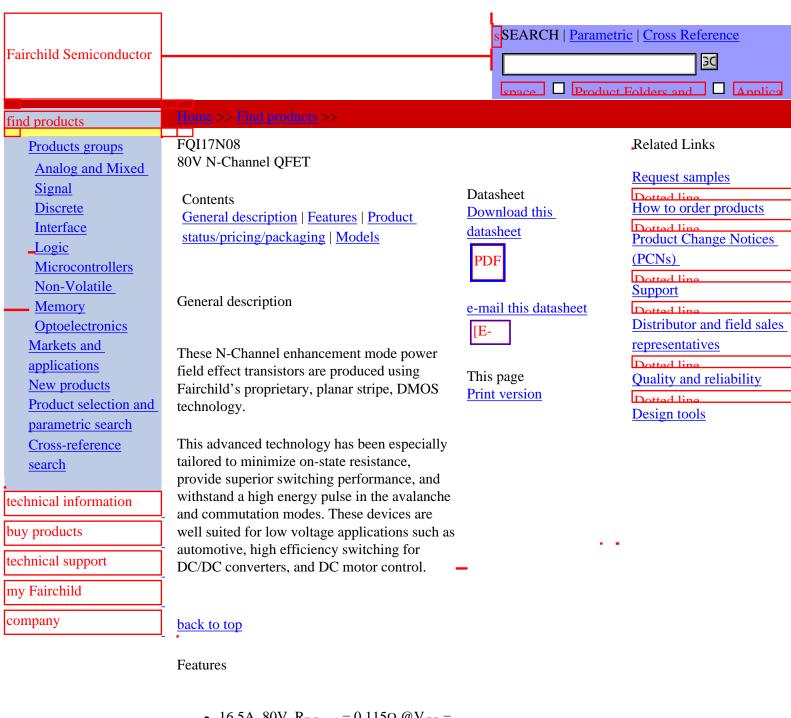
Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB17N08TM	Full Production	\$0.54	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI17N08TU	Full Production	\$0.54	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

Models

Package & leads Condition		Temperature range	Software version	Revision date	
PSPICE					
TO-262(I2PAK)-3	Electrical	-55°C to 175°C	9.2	Oct 5, 2001	

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